



## DECLARATION FOR PATENT APPLICATION

Attorney Docket:  
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As a below-named inventor(s), I/we hereby declare that:

My/Our residence(s), post office address(es) and citizenship(s) is/are as stated below next to my/our name(s).

I/We believe I/we am/are the original inventor, first and sole (if only one name is listed below) or the original, first and joint inventors (if plural names are listed below) of the subject matter which is claimed, and for which a patent is sought on the invention entitled: **Fan Out Type Wafer Level Package Structure and Method of the Same**

the specification of which: (check one)

☐ is attached hereto.☒ was filed on Dec. 3, 2003, as Serial No. 10/725,933,

and was amended on \_\_\_\_\_ (if applicable).

We hereby state that we have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the patentability of this application as defined by 37 CFR ' 1.56.

We hereby claim foreign priority benefits under 35 U.S.C. ' 119 of any foreign application(s) for patent or inventor's certificate listed below, and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

## Prior Foreign Applications:

_____ (Application No.)	_____ (Country)	_____/_____/_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Application No.)	_____ (Country)	_____/_____/_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Application No.)	_____ (Country)	_____/_____/_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No

We hereby appoint Gary M. Nath, Reg. No. 26,965; Harold L. Novick, Reg. No. 26,011; Todd L. Juneau, Reg. No. 40,669; Lee C. Heiman, Reg. No. 41,827; Jerald L. Meyer, Reg. No. 41,194; Joshua B. Goldberg, Reg. No. 44,126; Marvin C. Berkowitz, Reg. No. 47,421; Sheldon McGee, Reg. No. 50,454; Tanya E. Harkins, Reg. No. 52,993; Robert C. Ryan, Reg. No. 29,343; and Derek Richmond, Reg. No. 45,771; as my attorneys to prosecute this application and transact all business in the U.S. Patent and Trademark Office connected therewith.

Direct Telephone Calls to:

Gary M. Nath  
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Send Correspondence to:  
**NATH & ASSOCIATES, PLLC**  
Sixth Floor  
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Washington, D.C. 20005 U.S.A.

We hereby claim the benefit under 35 U.S.C. ' 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by 35 U.S.C. ' 112, first paragraph, I/we acknowledge the duty to disclose material information as defined in 37 CFR ' 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

_____ (U.S. Application Serial No.)	_____ (U.S. Filing Date)	_____ (Status--patented, pending, abandoned)
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_____ (U.S. Application Serial No.)	_____ (U.S. Filing Date)	_____ (Status--patented, pending, abandoned)
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I/we hereby claim the benefit under 35 U.S.C. 119(e) of any United States provisional application(s) listed below:

Application Number(s)

Filing Date

We hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. ' 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor: Wen-Kun YangInventor's Signature Wen-Kun Yang

Date:

12/8/03Residence: No. 47, Lane 6, Ankang St., Hsinchu, Taiwan 300, R.O.C.Country of Citizenship: Taiwan (R. O. C.)

Post Office Address: \_\_\_\_\_

Full name of second inventor: Wen-Pin YangInventor's Signature W. P. Yang

Date:

12/12/03Residence: No. 112, Julian St., Hsinchu, Taiwan 300, R.O.C.Country of Citizenship: Taiwan (R. O. C.)

Post Office Address: \_\_\_\_\_

Full name of third inventor: Shih-Li ChenInventor's Signature Shih-Li Chen

Date:

12/11/03Residence: 7F., No.22, Sanchong Rd., Jhudong Township, Hsinchu County, Taiwan 310, R.O.C.Country of Citizenship: Taiwan (R. O. C.)

Post Office Address: \_\_\_\_\_